

# Declaration of Compliance

We declare that our green products for customer comply with all RoHS regulations. We are willing to provide all necessary documentation or information to prove our compliance with the RoHS regulations. It is our responsibility to proactively inform our customer if we identify that there is a potential risk of breaching the RoHS regulations in our product.

## 1. Product Information:

Model P/N:	Products P/N:
F0PEC4630503Z	4610-30T-O-AC-F-JP v1
F0PEC4630403Z	4610-30T-O-AC-F-US v1
F0PEC4630303Z	4610-30T-O-AC-F-UK v1
F0PEC4630203Z	4610-30T-O-AC-F-EU v1
F0PEC4630004Z	4610-30T-O-48V-F v1
F0PEC4630003Z	4610-30T-O-AC-F v1

Product meets EU RoHS requirements by application of selected exemption(s):

Banned Substance	Threshold Limit	RoHS Exemption*
Lead (Pb)	1,000 ppm (0.1 weight %)	6(c); 7(a); 7(c)-I
Cadmium (Cd)	100 ppm (0.01 weight %)	
Mercury (Hg)	1,000 ppm (0.1 weight %)	
Hexavalent Chromium (Cr <sup>6+</sup> )	1,000 ppm (0.1 weight %)	
Poly Brominated Biphenyls (PBB)	1,000 ppm (0.1 weight %)	
Poly Brominated Diphenyl Ethers (PBDE)	1,000 ppm (0.1 weight %)	
Bis(2-Ethylhexyl) phthalate (DEHP)	1,000 ppm (0.1 weight %)	
Benzyl butyl phthalate (BBP)	1,000 ppm (0.1 weight %)	
Dibutyl phthalate (DBP)	1,000 ppm (0.1 weight %)	
Diisobutyl phthalate (DIBP)	1,000 ppm (0.1 weight %)	

RoHS maximum limit (ppm) does not apply to applications for which exemptions have been granted by the RoHS Directive.

Applicable within the scope of categories and expiry dates as given in Annex III of Directive 2011/65/EU as listed below:

RoHS exemption	RoHS exemption description
6(c)	Copper alloy containing up to 4% lead by weight.
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

This statement reflects Products listed below that are manufactured by Edgecore Technology Corporation are in compliance to Regulation (EC) No 1907/2006 of the European Parliament and of the Council of 18 December 2006 concerning the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH). The Candidate List of SVHCs is continually updated at <https://echa.europa.eu/candidate-list-table>.

This product contains the following REACH Substances of Very High Concern above the limits (0.1% w/w) of component article within REACH:

CAS No.	SVHCs in a concentration above 0.1% weight by weight
101-77-9	4,4'- Diaminodiphenylmethane (MDA)
10043-35-3	Boric acid
1303-86-2	Diboron trioxide
1317-36-8	Lead monoxide (lead oxide)
123-77-3	Diazene-1,2-dicarboxamide (C,C'-azodi(formamide)) (ADCA)
25550-51-0	Hexahydromethylphthalic anhydride
7439-92-1	Lead
71868-10-5	2-methyl-1-(4-methylthiophenyl)-2-morpholinopropan-1-one

Table of toxic and hazardous substances/elements and their content:

(As required by China's management methods for controlling pollution by electronic information products)

产品内含危害物质揭露表 Products contain hazardous substances exposing table						
零部件名称 Component Name	危害物质项目 Hazardous Substances Project					
	铅 (Pb)	镉 (Cd)	汞 (Hg)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯乙醚 (PBDE)
电源供应器 Power supply	X	○	○	○	○	○
电源线 Power Cord	X	○	○	○	○	○
间隔柱 SPACER	X	○	○	○	○	○
固态硬盘模块 eUSB MODULE	X	○	○	○	○	○
场效应晶体管 Mosfet	X	○	○	○	○	○
终端连接器 Terminal	X	○	○	○	○	○
电压转换集成电路 Regulator	X	○	○	○	○	○
二极管 Diode	X	○	○	○	○	○
电阻 Resistor	X	○	○	○	○	○
本表格依据 SJ/T : 11364-2014 的规定编制。						
○ : 表示此部件使用的所有同类材料中此种有毒或有害物质的含量均低于 GB/T 26572-2011 规定的限制要求。 ○ : indicates the toxic or hazardous substance content of the part (at the homogenous material level) is lower than the threshold defined by Requirements for Concentration Limits for Toxic or hazardous Substances in Electronic Information Products (GB/T 26572-2011) issued by Chinese Ministry of Information Industry ("Not Contained" toxic or hazardous substances).						
X:表示此部件使用的至少一种同类材料中, 此种有毒或有害物质的含量高于 GB/T 26572-2011 规定的限制要求。 X: indicates the toxic or hazardous substance content of the part (at the homogenous material level) is over the threshold defined by standard of GB/T 26572-2011 ("Contained" toxic or hazardous substances). Suppliers can explain the technical cause of "X" according to actual situation.						

The declared Edgecore product(s) is (are) in compliance with the restriction identified in Article 11:

Banned Substance	Threshold Limit
Lead (Pb)	1,000 ppm (0.1 weight %)
Cadmium (Cd)	100 ppm (0.01 weight %)
Mercury (Hg)	1,000 ppm (0.1 weight %)
Hexavalent Chromium (Cr <sup>6+</sup> )	1,000 ppm (0.1 weight %)
Poly Brominated Biphenyls (PBB)	1,000 ppm (0.1 weight %)
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The following tables are a declaration of the presence condition of restricted substances:

設備名稱：1G乙太網路交換機 Equipment name		型號（型式）：A54610-30T Type designation (Type)				
單元 Unit	限用物質及其化學符號 Restricted substances and its chemical symbols					
	鉛Lead (Pb)	汞Mercury (Hg)	鎘Cadmium (Cd)	六價鉻Hexavalent chromium (Cr+6)	多溴聯苯Polybrominated biphenyls (PBB)	多溴二苯醚Polybrominated diphenyl ethers (PBDE)
電路板組件 PCBA	-	○	○	○	○	○
機殼 Chassis	-	○	○	○	○	○
線材 Cable Assy	○	○	○	○	○	○
電源線 Power Cord	-	○	○	○	○	○
電源供應器 Power Supply	-	○	○	○	○	○
<p>備考1. “超出0.1 wt %” 及 “超出0.01 wt %” 係指限用物質之百分比含量超出百分比含量基準值。            Note 1: “Exceeding 0.1 wt %” and “exceeding 0.01 wt %” indicate that the percentage content of the restricted substance exceeds the reference percentage value of presence condition.</p> <p>備考2. “○” 係指該項限用物質之百分比含量未超出百分比含量基準值。            Note 2: “○” indicates that the percentage content of the restricted substance does not exceed the percentage of reference value of presence.</p> <p>備考3. “-” 係指該項限用物質為排除項目。            Note 3: The “-” indicates that the restricted substance corresponds to the exemption.</p>						

Name: 陳文輝 Wen Chen  
 Deputy Project Manager  
 QA Representative

Signature :

Date : 2022-08-12

Wm. A. R.